US00D684551S

(12) **United States Design Patent**
Nguyen

(10) **Patent No.:** **US D684,551 S**
(45) **Date of Patent:** ** **Jun. 18, 2013**

---

(54) **WAFER POLISHING PAD HOLDER**

(76) Inventor: **Phuong Van Nguyen**, San Jose, CA (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/396,846**

(22) Filed: **Jul. 7, 2011**

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/E21, 21, E21.23; 361/234; 451/72, 285, 286, 287, 288
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2,740,237 A		4/1956	Day et al.	
4,081,928 A		4/1978	Kinnebrew et al.	
4,165,584 A		8/1979	Scherrer	
4,512,113 A		4/1985	Budinger	
4,780,991 A		11/1988	Gosis	
5,193,316 A		3/1993	Olmstead	
5,533,924 A		7/1996	Stroupe et al.	
5,597,346 A		1/1997	Hempel, Jr.	
5,647,789 A		7/1997	Kitta et al.	
5,788,560 A		8/1998	Hashimoto et al.	
6,402,594 B1	*	6/2002	Kobayashi et al.	451/41
6,425,809 B1	*	7/2002	Ichimura	451/287
6,612,905 B2		9/2003	Nguyen	
6,645,049 B2		11/2003	Nguyen	
6,699,104 B1	*	3/2004	Baker et al.	451/28
6,722,949 B2	*	4/2004	Hu et al.	451/36
6,887,138 B2		5/2005	Bottema et al.	
7,462,094 B2	*	12/2008	Yoshida et al.	451/41
7,534,162 B2	*	5/2009	Bottema et al.	451/41
7,572,173 B2	*	8/2009	Huang et al.	451/285
7,632,170 B2	*	12/2009	O'Moore et al.	451/65
D609,652 S	*	2/2010	Nagasaka et al.	D13/182
7,731,567 B2	*	6/2010	Sekiya et al.	451/11
D633,452 S	*	3/2011	Namiki et al.	D13/182
2002/0160693 A1	*	10/2002	Nihonmatsu et al.	451/41
2004/0053566 A1	*	3/2004	Tolles et al.	451/285
2005/0041234 A1	*	2/2005	Krikhaar et al.	355/72
2005/0095963 A1	*	5/2005	Stark et al.	451/259
2005/0170616 A1	*	8/2005	Murata et al.	438/463
2006/0079160 A1	*	4/2006	Balagani et al.	451/285

FOREIGN PATENT DOCUMENTS

JP	2005033139	2/2005
JP	2010105144	5/2010
KR	100928450	11/2009

* cited by examiner

Primary Examiner — Selina Sikder
(74) *Attorney, Agent, or Firm* — Michael I. Kroll

(57) **CLAIM**

The ornamental design for a wafer polishing pad holder, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of the wafer polishing pad holder showing my new design;

FIG. **2** is a top view of the wafer polishing pad holder showing my new design;

FIG. **3** is a front view of the wafer polishing pad holder showing my new design;

FIG. **4** is a rear view of the wafer polishing pad holder showing my new design;

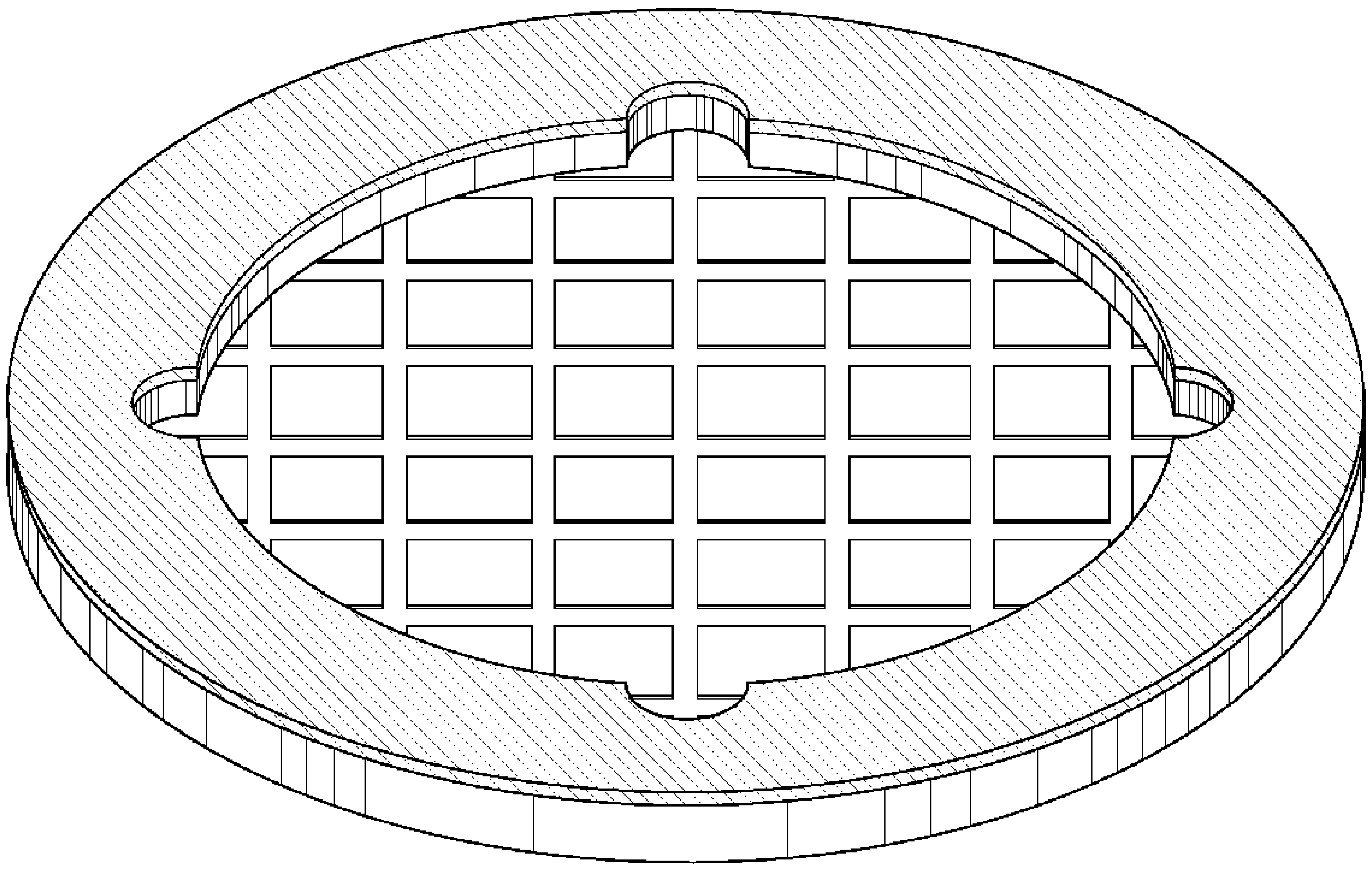
FIG. **5** is a right side view of the wafer polishing pad holder showing my new design;

FIG. **6** is a left side view of the wafer polishing pad holder showing my new design; and

FIG. **7** is a cross sectional view of the wafer polishing pad holder, taken from FIG. **2** as indicated showing my new design; and,

FIG. **8** is a top view of the wafer polishing pad holder without the milled island within the inside pocket showing my new design.

1 Claim, 8 Drawing Sheets



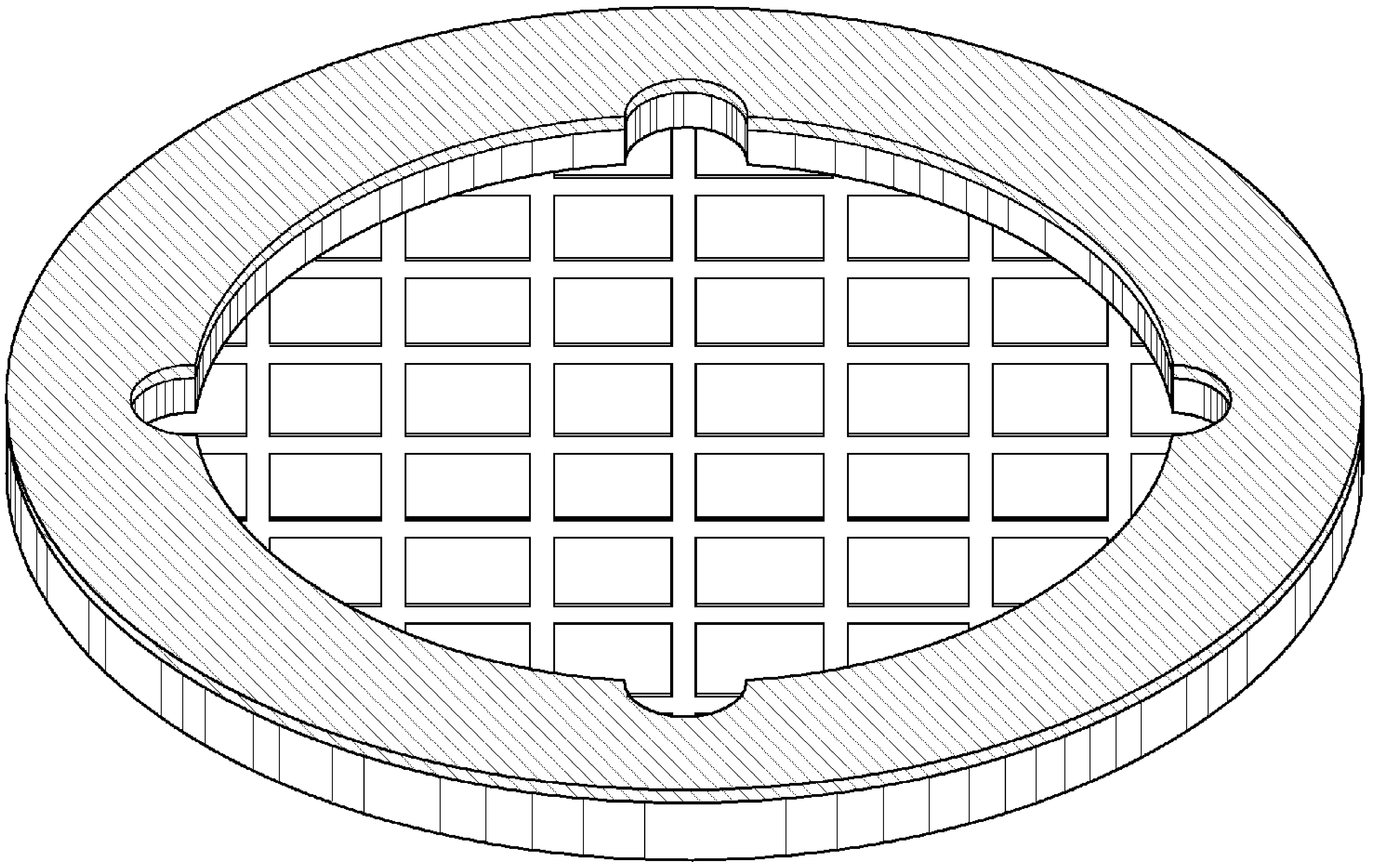


FIG. 1

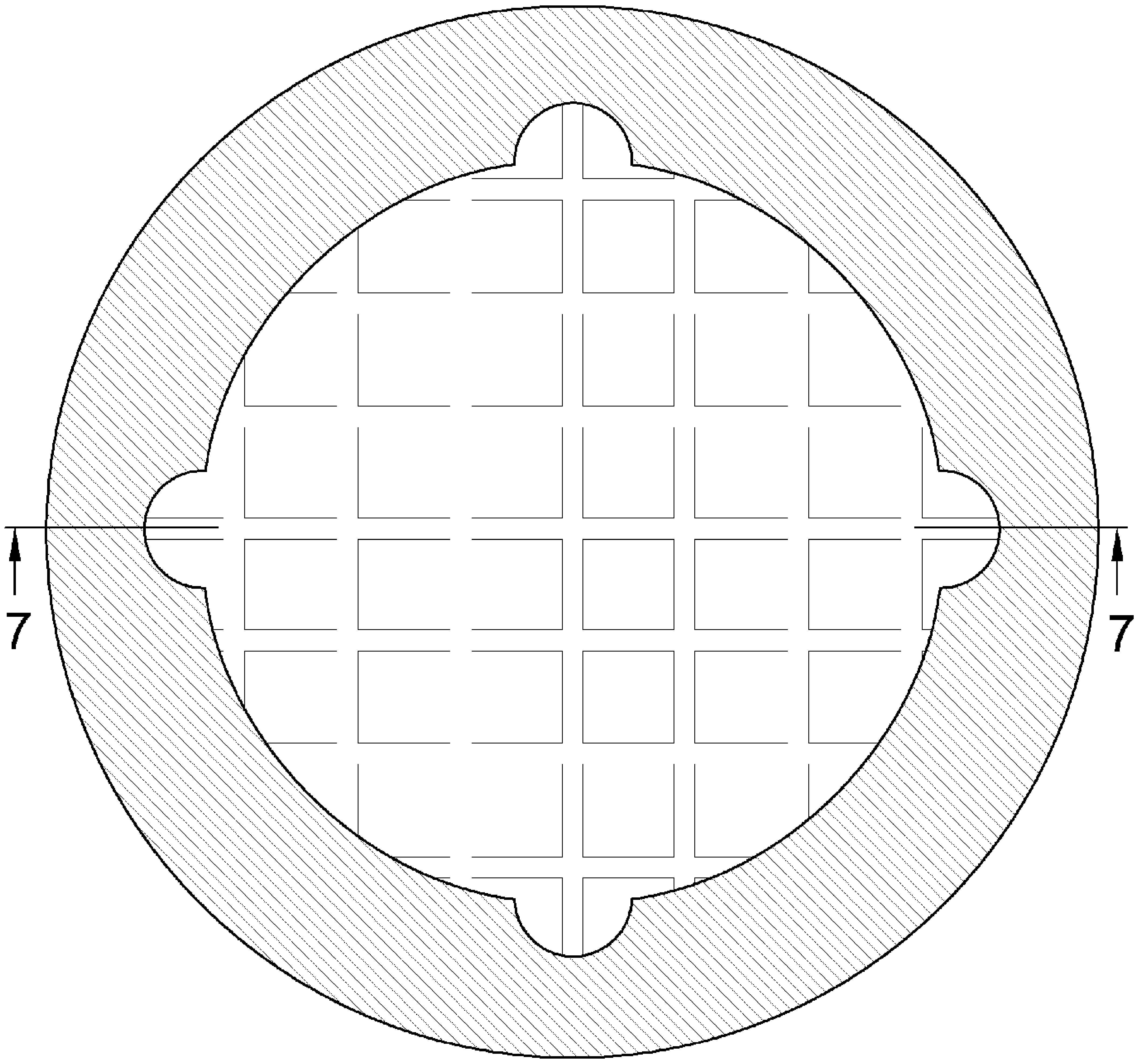


FIG. 2

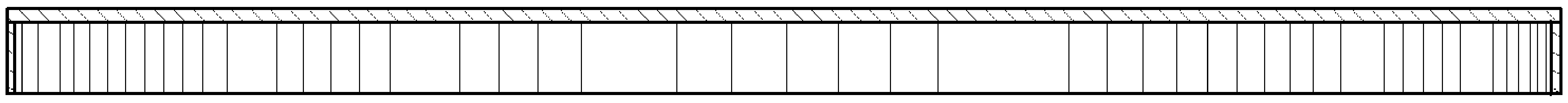


FIG. 3

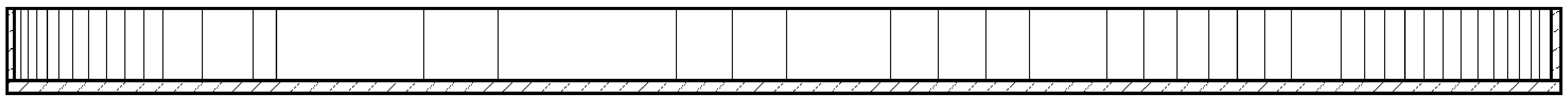


FIG. 4

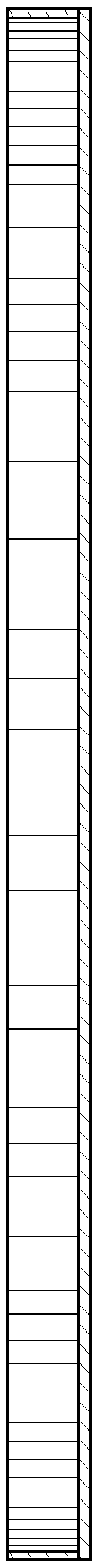


FIG. 5

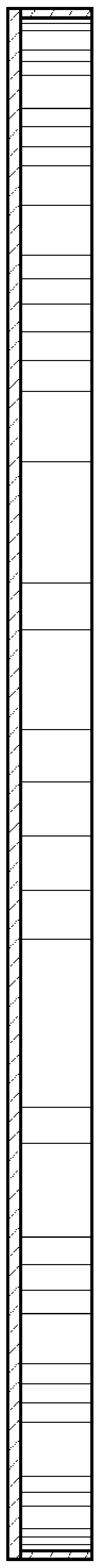


FIG. 6

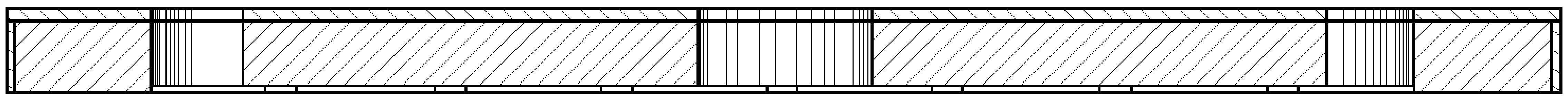


FIG. 7

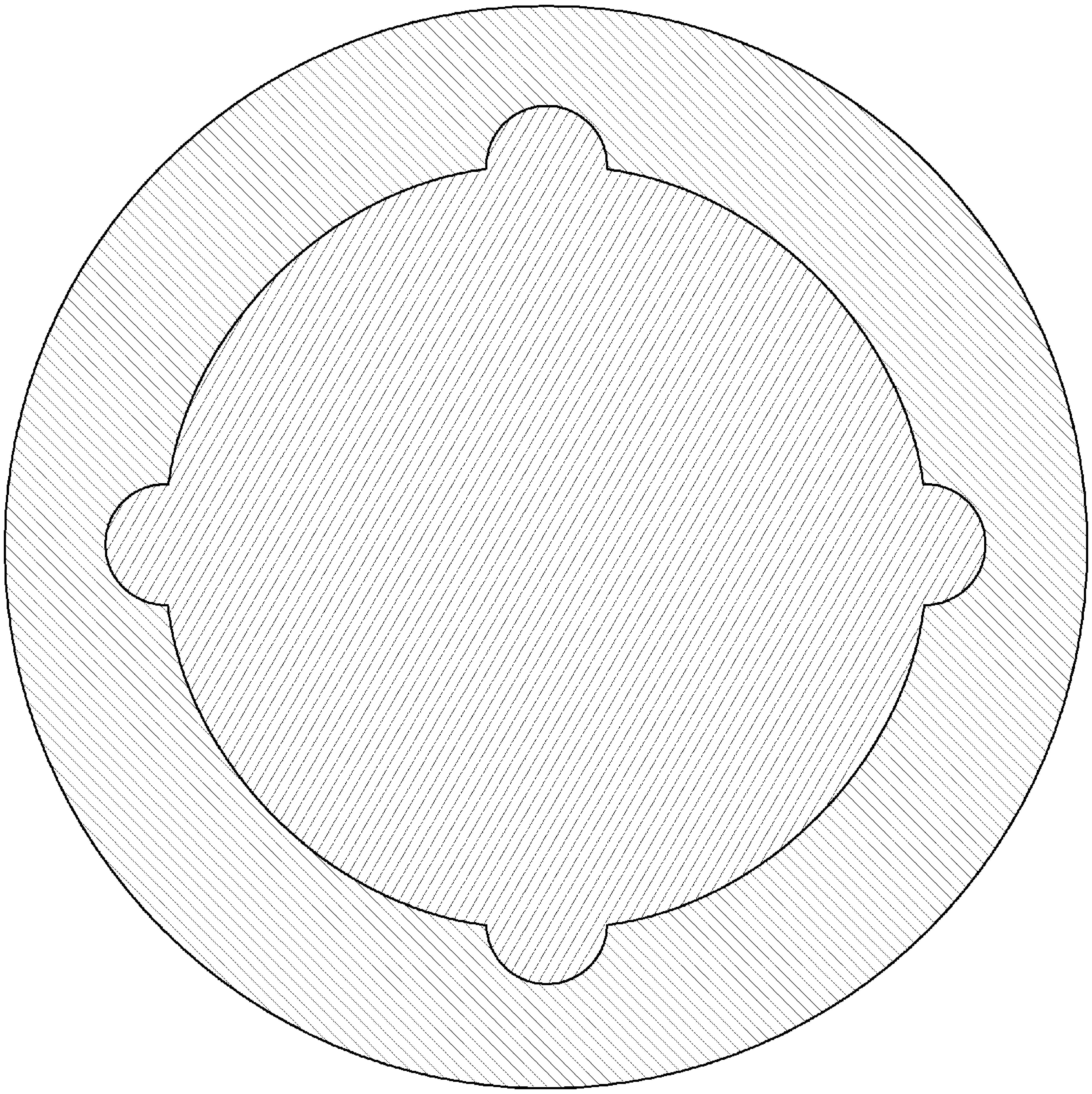


FIG. 8